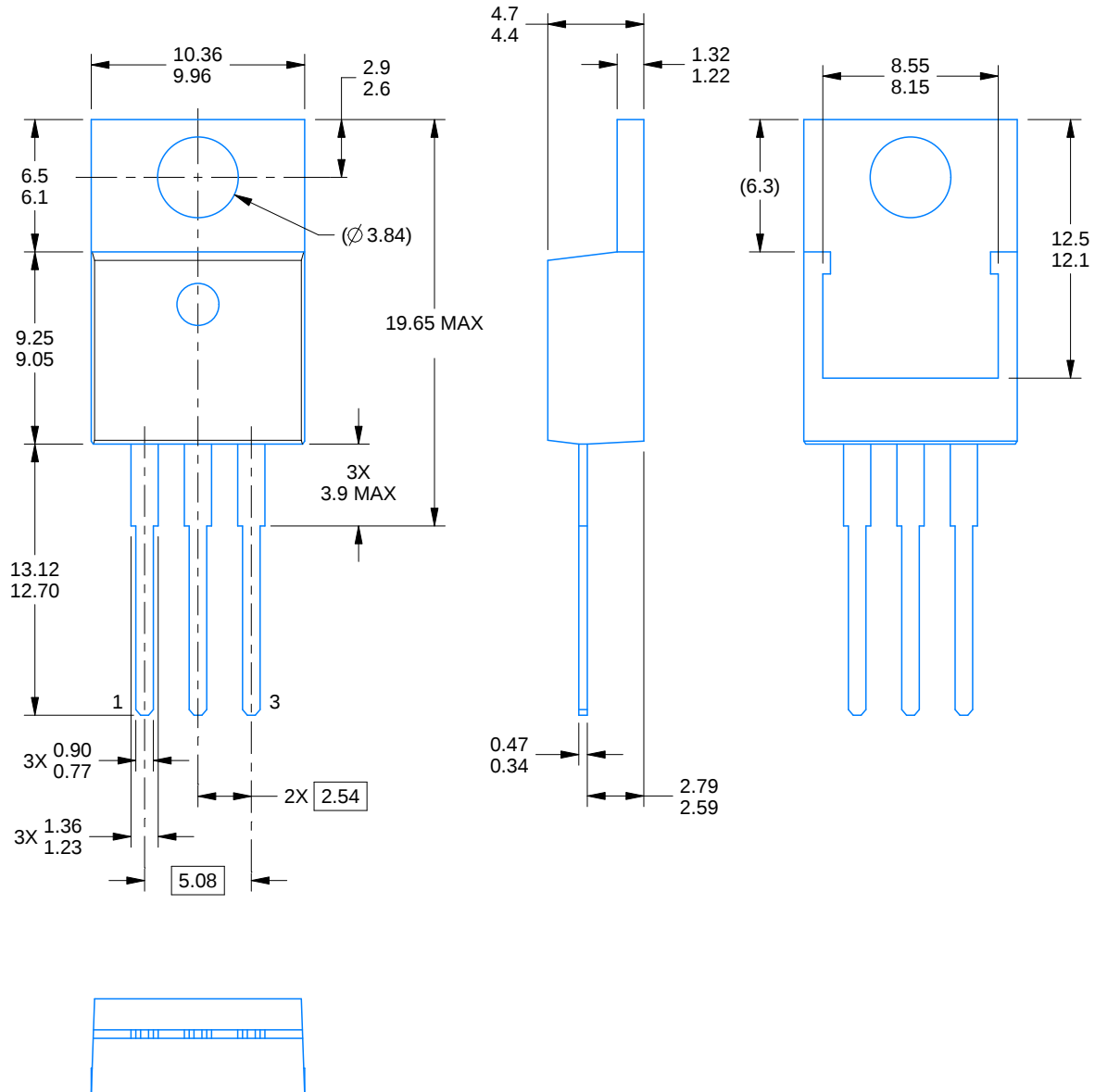


PACKAGE OUTLINE

KCS0003B

TO-220 - 19.65 mm max height

TO-220



4222214/B 08/2018

NOTES:

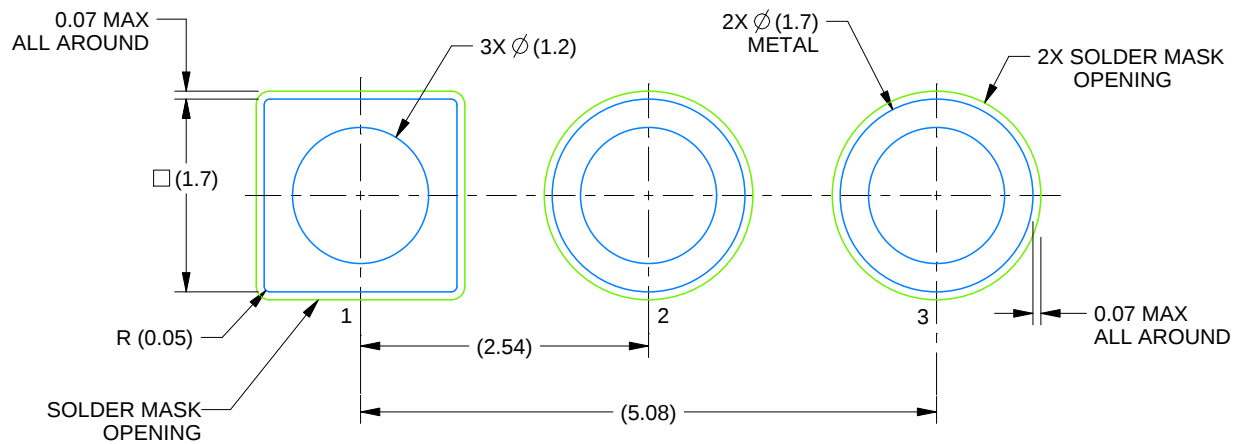
1. Dimensions are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-220.

EXAMPLE BOARD LAYOUT

KCS0003B

TO-220 - 19.65 mm max height

TO-220



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:15X

4222214/B 08/2018

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2151829	10/22/2015	J. NOQUIL / T. LEQUANG
A	CORRECT NOTE 1	2175971	08/17/2018	E. PREISS / K. SINCERBOX

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